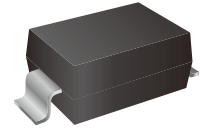


Surface Mount Schottky Barrier Rectifier

Features

- The plastic package carries Underwriters Laboratory Flammability Classification 94V-0
- For surface mounted applications
- Metal silicon junction, majority carrier conduction
- Low power loss, high efficiency
- Built-in strain relief, ideal for automated placement
- High forward surge current capability
- Lead free in comply with EU RoHS 2011/65/EU directives



Mechanical Data

- Case: SMAW
- Terminal: Leads solderable per MIL-STD-750 Method 2026
- Polarity: Color band denotes cathode end
- Mounting Position: Any

Ordering Information

Part Number	Shipping	Reel
LT12AW THRU LT120AW	8000PCS Tape&Reel	13 inches

Maximum Ratings and Electrical Characteristics

Ratings at 25°C ambient temperature unless otherwise specified.
 Single phase half-wave 60Hz, resistive or inductive load, for capacitive load current derate by 20%.

Parameter	Symbol	LT12AW	LT14AW	LT16AW	LT18AW	LT110AW	LT112AW	LT115AW	LT120AW	Unit	
	Marking	S12W	S14W	S16W	S18W	S110W	S112W	S115W	S120W		
Maximum repetitive peak reverse voltage	V_{RRM}	20	40	60	80	100	120	150	200	V	
Maximum RMS voltage	V_{RMS}	14	28	42	56	70	84	105	140	V	
Maximum DC blocking voltage	V_{DC}	20	40	60	80	100	120	150	200	V	
Maximum instantaneous forward voltage at 1A	V_F	0.55	0.55	0.7	0.85	0.85	0.85	0.9	0.9	V	
Maximum average forward rectified current at T_L (see fig.1)	$I_{(AV)}$	1								A	
Peak forward surge current 8.3ms single half sine-wave superimposed on rated load (JEDEC Method)	I_{FSM}	30								A	
Maximum DC reverse current $T_A=25^\circ\text{C}$ at rated DC blocking voltage $T_A=100^\circ\text{C}$	I_R	0.3 10			0.2 5			0.1 2		mA	
Typical Junction Capacitance (Note1)	C_J	110			80					pF	
Typical thermal resistance (Note2)	$R_{\theta JA}$	90									°C/W
Operating junction temperature range	T_J	-55 to +125									°C
Storage temperature range	T_{STG}	-55 to +150									°C

Note: (1) Measured at 1MHz and applied reverse voltage of 4.0V D.C.
 (2) P.C.B. mounted with 2.0" x 2.0" (5.0cm x 5.0cm) copper pad areas.



Ratings and Characteristics Curves

FIG.1 FORWARD CURRENT DERATING CURVE

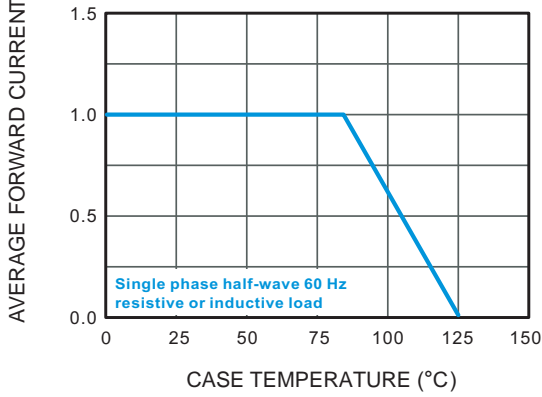


FIG.2 TYPICAL REVERSE CHARACTERISTICS

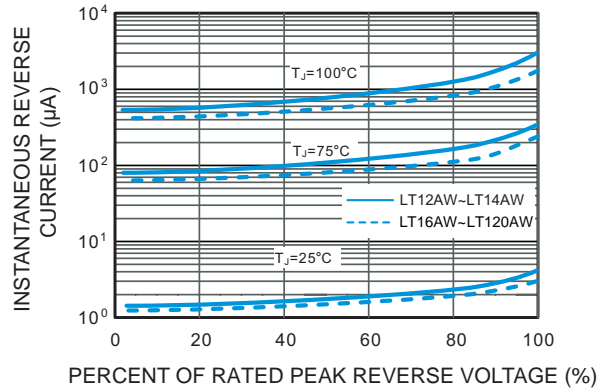


FIG.3 TYPICAL FORWARD CHARACTERISTICS

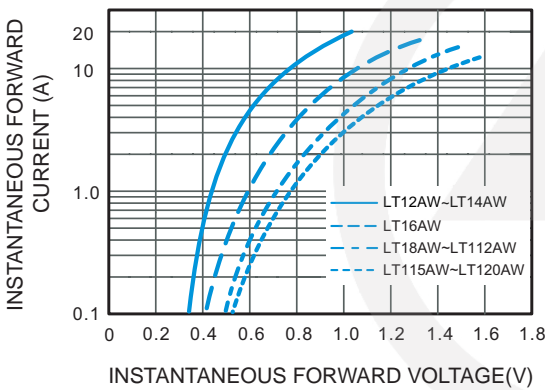


FIG.4 TYPICAL JUNCTION CAPACITANCE

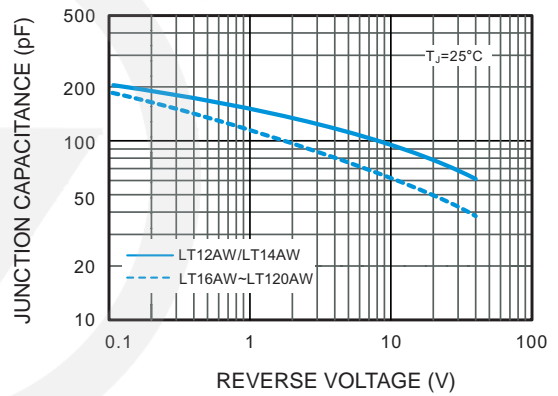


FIG.5 MAXIMUM NON-REPETITIVE PEAK FORWARD SURGE CURRENT

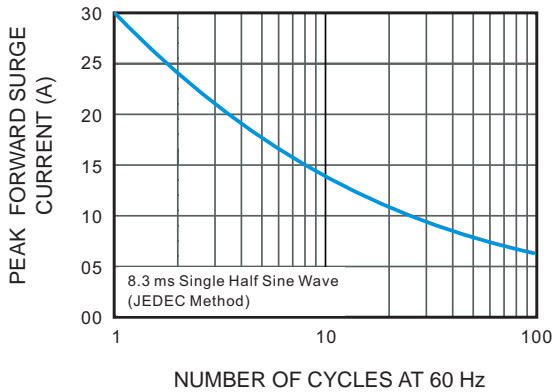
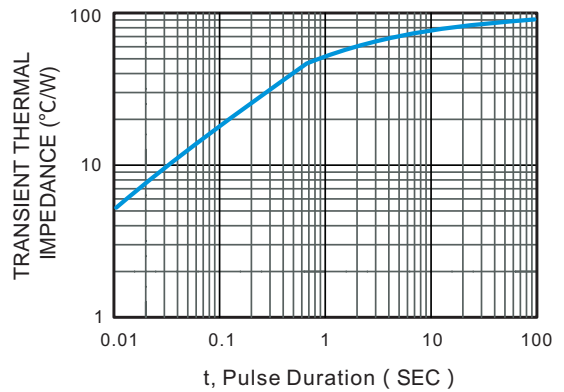
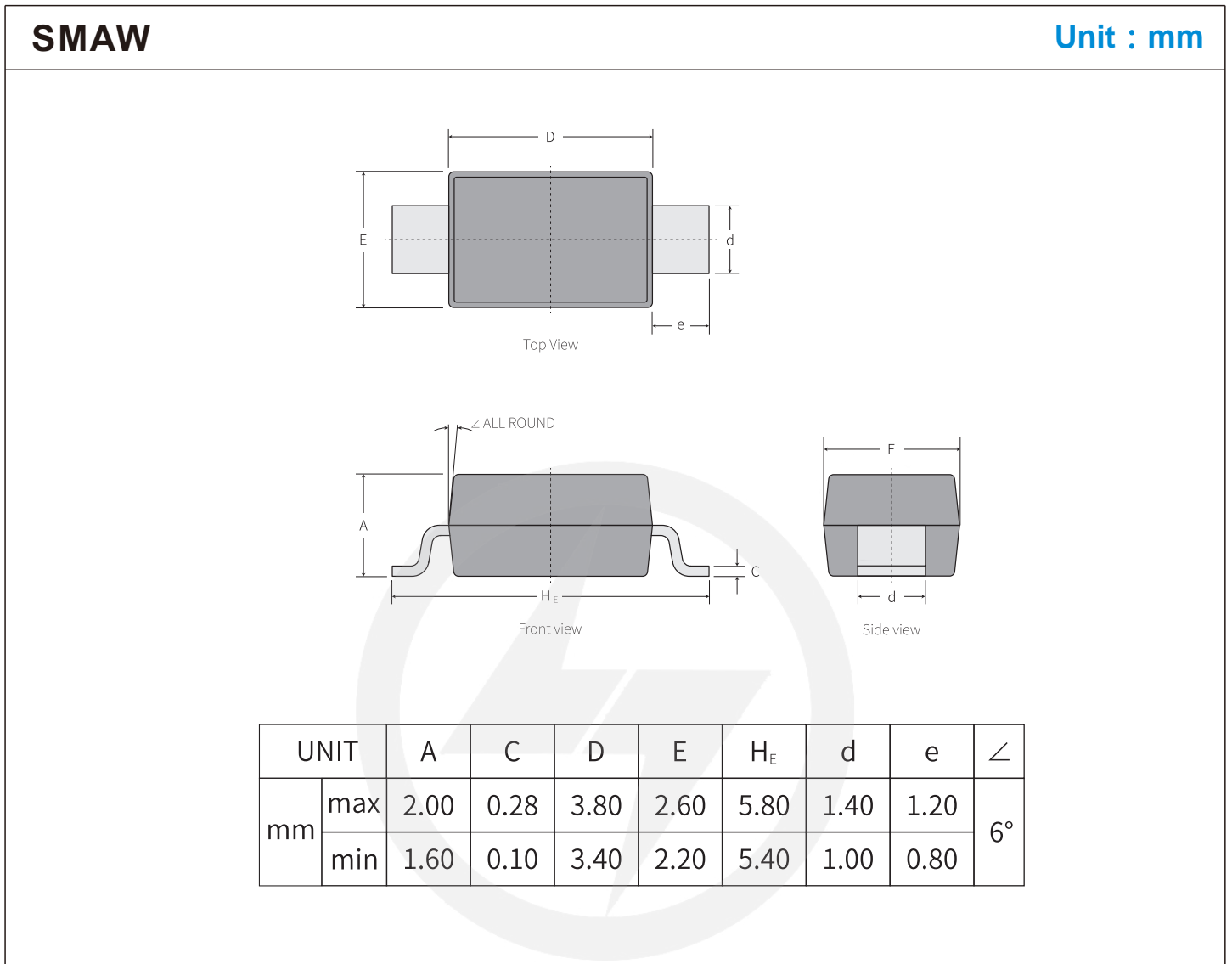


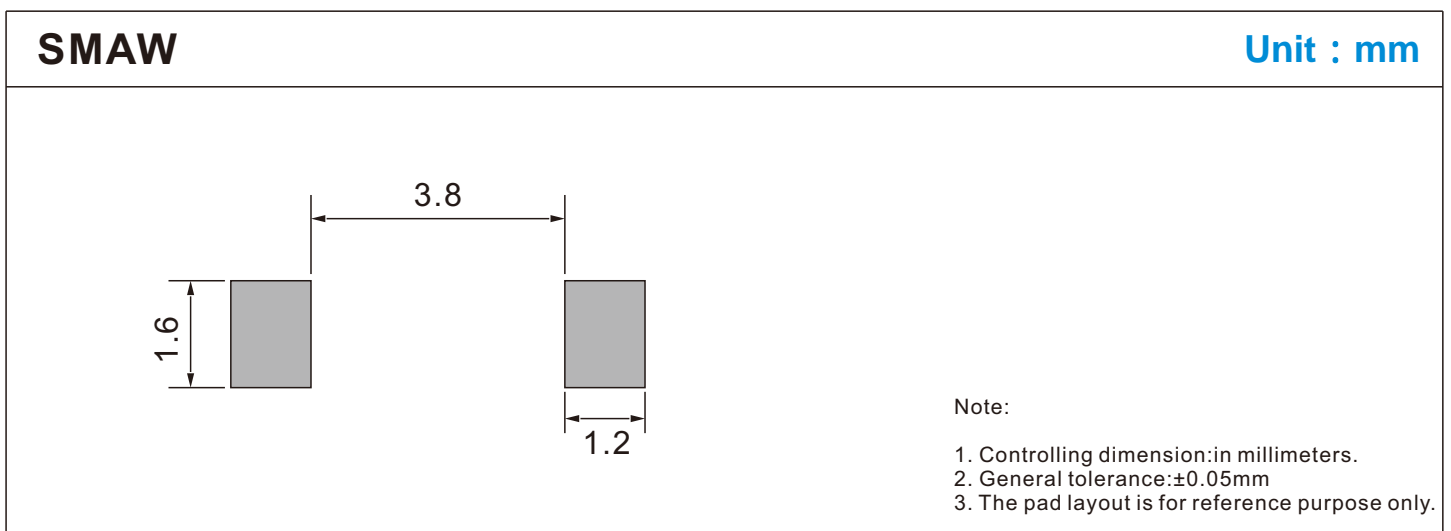
FIG.6 TYPICAL TRANSIENT THERMAL IMPEDANCE



Package Outline

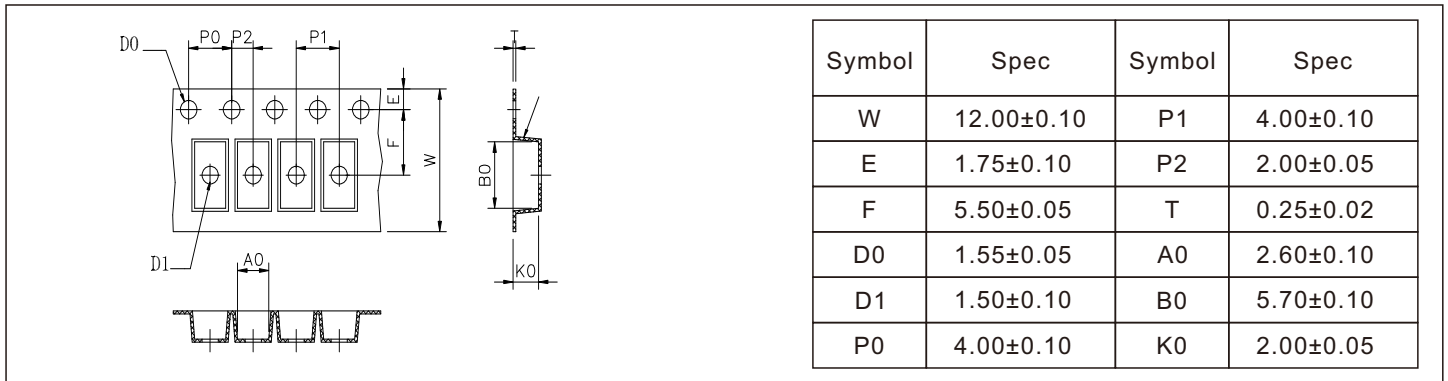


Suggested Pad Layout



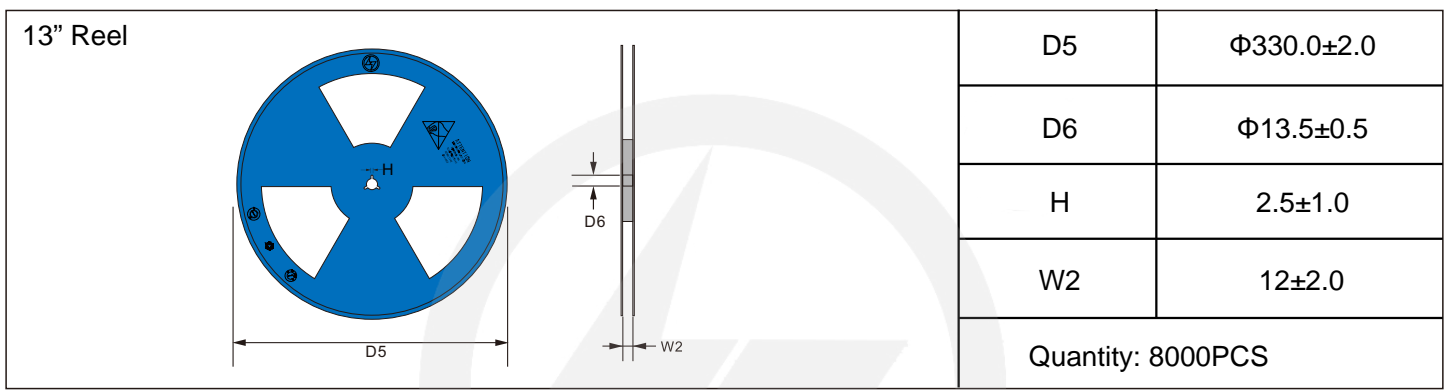
Carrier Tape Dimensions

Unit : mm

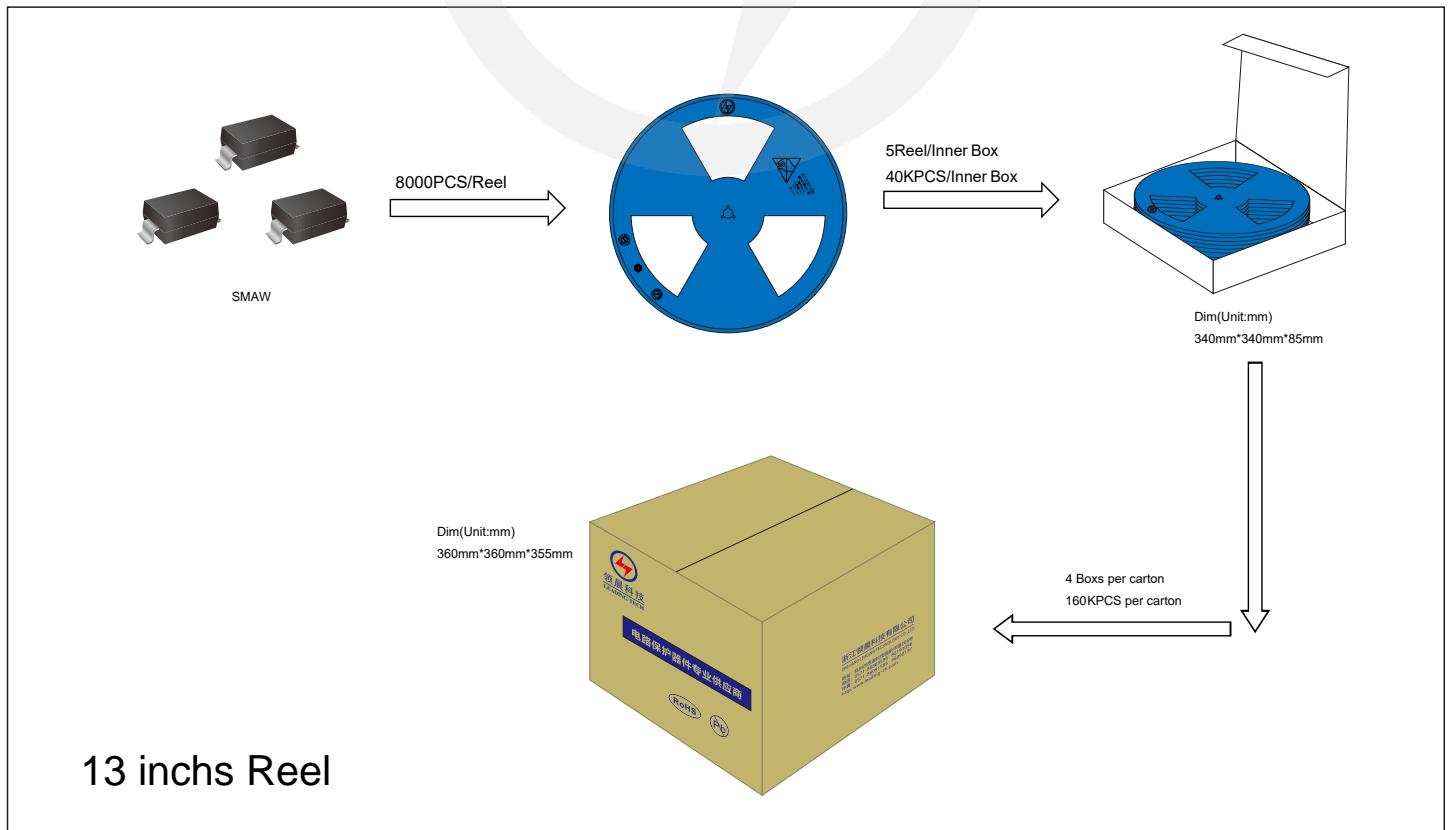


Reel Dimensions

Unit : mm



Packaging





Recommended Soldering Conditions



Recommended Conditions

Profile Feature	Pb-Free Assembly
Average ramp-up rate (T _L to T _P)	3°C/second max.
Preheat	
-Temperature Min (T _{S min})	150°C
-Temperature Max (T _{S max})	200°C
-Time (min to max) (t _s)	60-180 seconds
T _{S max} to T _L	
-Ramp-up Rate	3°C/second max.
Time maintained above:	
-Temperature (T _L)	217°C
-Time (t _L)	60-150 seconds
Peak Temperature (T _P)	260°C
Time within 5°C of actual Peak Temperature (t _p)	20-40 seconds
Ramp-down Rate	6°C/second max.
Time 25°C to Peak Temperature	8 minutes max.

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Version Update Information

Series NO.	Enactment/Revision Date	Effective Date	Version	Revision content	Revision Reason	Revision Person	Note
01	2023.11.30	2023.11.30	1.0	New File	/	Ding	
02	2025.06.30	2025.06.30	1.1	Update packaging information	/	Ding	